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Details

Product Status	Obsolete
Core Processor	H8/300L
Core Size	8-Bit
Speed	5MHz
Connectivity	SCI
Peripherals	LCD, PWM, WDT
Number of I/O	51
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	85-TFLGA
Supplier Device Package	85-TFLGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/hd64f38024rlpv

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H8/38024, H8/38024S, H8/38024R, H8/38124 Group

Hardware Manual

Renesas 8-Bit Single-Chip Microcomputer

H8 Family/H8/300L Super Low Power Series

H8/38024 Group	H8/38024	H8/38024R Group	H8/38024R
	H8/38023		
	H8/38022		
	H8/38021		
	H8/38020		
H8/38024S Group	H8/38024S	H8/38124 Group	H8/38124
	H8/38022S		H8/38123
	H8/38021S		H8/38122
	H8/38020S		H8/38121
	H8/38000S		H8/38120

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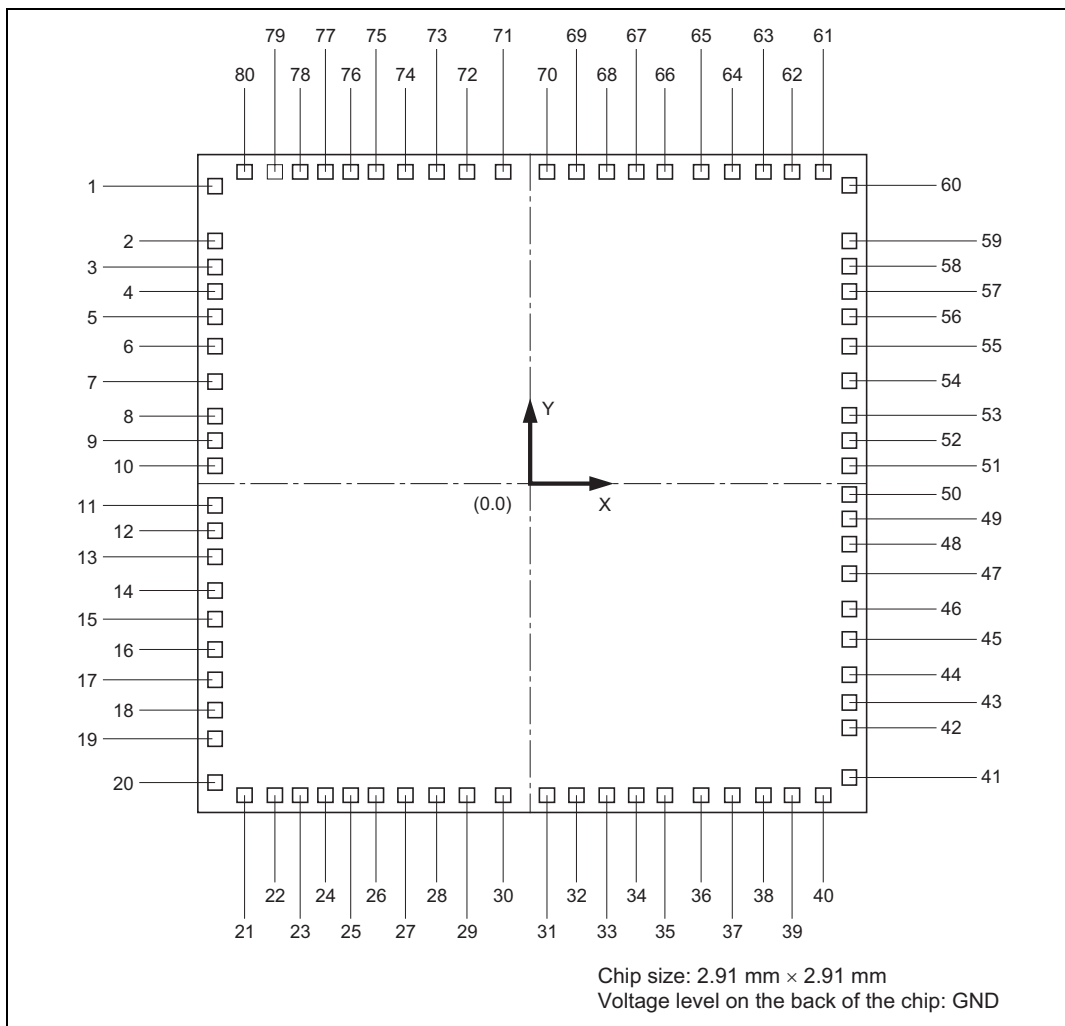


Figure 1.7 Bonding Pad Location Diagram of HCD64338024S, HCD64338023S, HCD64338022S, HCD64338021S, and HCD64338020S (Top View)

1.3.2 Pin Functions

Table 1.5 outlines the pin functions of the H8/38024 Group.

Table 1.5 Pin Functions

Type	Symbol	Pin No.			Pad No. *1	Pad No. *2	Pad No. *3	I/O	Name and Functions
		FP-80A TFP-80C	FP-80B	TLP-85V					
Power source pins	V _{CC}	52	54	E8	53	54	52	Input	Power supply: All V _{CC} pins should be connected to the system power supply.
	V _{SS}	8 (= AV _{SS}) 53	10 (= AV _{SS}) 55	D8 E1 (= AV _{SS})	9 54	10 55	8 53	Input	Ground: All V _{SS} pins should be connected to the system power supply (0 V).
	AV _{CC}	1	3	B1	1	2	1	Input	Analog power supply: This is the power supply pin for the A/D converter. When the A/D converter is not used, connect this pin to the system power supply.
	AV _{SS}	8 (= V _{SS})	10 (= V _{SS})	E1 (= V _{SS})	8	9	8	Input	Analog ground: This is the A/D converter ground pin. It should be connected to the system power supply (0V).
	V ₁ V ₂ V ₃	51 50 49	53 52 51	F9 E9 F8	52 51 50	53 52 51	51 50 49	Input	LCD power supply: These are the power supply pins for the LCD controller/driver.
	CV _{CC} *4	4	—	—	—	—	—	Input	Power supply: This is the internal step-down power supply pin. To ensure stability, a capacitor with a rating of about 0.1 μF should be connected between this pin and the V _{SS} pin.

Register Indirect with Post-Increment or Pre-Decrement—@Rn+ or @-Rn:

- Register indirect with post-increment—@Rn+

The @Rn+ mode is used with MOV instructions that load registers from memory.

The register field of the instruction specifies a 16-bit general register containing the address of the operand. After the operand is accessed, the register is incremented by 1 for MOV.B or 2 for MOV.W. For MOV.W, the original contents of the 16-bit general register must be even.

- Register indirect with pre-decrement—@-Rn

The @-Rn mode is used with MOV instructions that store register contents to memory.

The register field of the instruction specifies a 16-bit general register which is decremented by 1 or 2 to obtain the address of the operand in memory. The register retains the decremented value. The size of the decrement is 1 for MOV.B or 2 for MOV.W. For MOV.W, the original contents of the register must be even.

Absolute Address—@aa:8 or @aa:16: The instruction specifies the absolute address of the operand in memory.

The absolute address may be 8 bits long (@aa:8) or 16 bits long (@aa:16). The MOV.B and bit manipulation instructions can use 8-bit absolute addresses. The MOV.B, MOV.W, JMP, and JSR instructions can use 16-bit absolute addresses.

For an 8-bit absolute address, the upper 8 bits are assumed to be 1 (H'FF). The address range is H'FF00 to H'FFFF (65280 to 65535).

Immediate—#xx:8 or #xx:16: The instruction contains an 8-bit operand (#xx:8) in its second byte, or a 16-bit operand (#xx:16) in its third and fourth bytes. Only MOV.W instructions can contain 16-bit immediate values.

The ADDS and SUBS instructions implicitly contain the value 1 or 2 as immediate data. Some bit manipulation instructions contain 3-bit immediate data in the second or fourth byte of the instruction, specifying a bit number.

Program-Counter Relative—@(d:8, PC): This mode is used in the Bcc and BSR instructions. An 8-bit displacement in byte 2 of the instruction code is sign-extended to 16 bits and added to the program counter contents to generate a branch destination address. The possible branching range is -126 to +128 bytes (-63 to +64 words) from the current address. The displacement should be an even number.

Memory Indirect—@@aa:8: This mode can be used by the JMP and JSR instructions. The second byte of the instruction code specifies an 8-bit absolute address. The word located at this address contains the branch destination address.

8.10.4 Pin States

Table 8.28 shows the port A pin states in each operating mode.

Table 8.28 Port A Pin States

Pins	Reset	Sleep	Subsleep	Standby	Watch	Subactive	Active
PA ₃ /COM ₄	High-impedance	Retains	Retains	High-	Retains	Functional	Functional
PA ₂ /COM ₃		previous	previous	impedance	previous		
PA ₁ /COM ₂		state	state		state		
PA ₀ /COM ₁							

Bits 3 to 0—Internal Clock Select (TMA3 to TMA0)

Bits 3 to 0 select the clock input to TCA. The selection is made as follows.

Description						
Bit 3 TMA3	Bit 2 TMA2	Bit 1 TMA1	Bit 0 TMA0	Prescaler and Divider Ratio or Overflow Period	Function	
0	0	0	0	PSS, $\phi/8192$	(initial value) Interval timer	
			1	PSS, $\phi/4096$		
		1	0	PSS, $\phi/2048$		
			1	PSS, $\phi/512$		
	1	0	0	PSS, $\phi/256$		
			1	PSS, $\phi/128$		
		1	0	PSS, $\phi/32$		
			1	PSS, $\phi/8$		
1	0	0	0	PSW, 1 s	Clock time base (when using 32.768 kHz)	
			1	PSW, 0.5 s		
		1	0	PSW, 0.25 s		
			1	PSW, 0.03125 s		
	1	0	0	PSW and TCA are reset		
			1			
		1	0			
			1			

10.1.2 Block Diagram

Figure 10.1 shows a block diagram of SCI3.

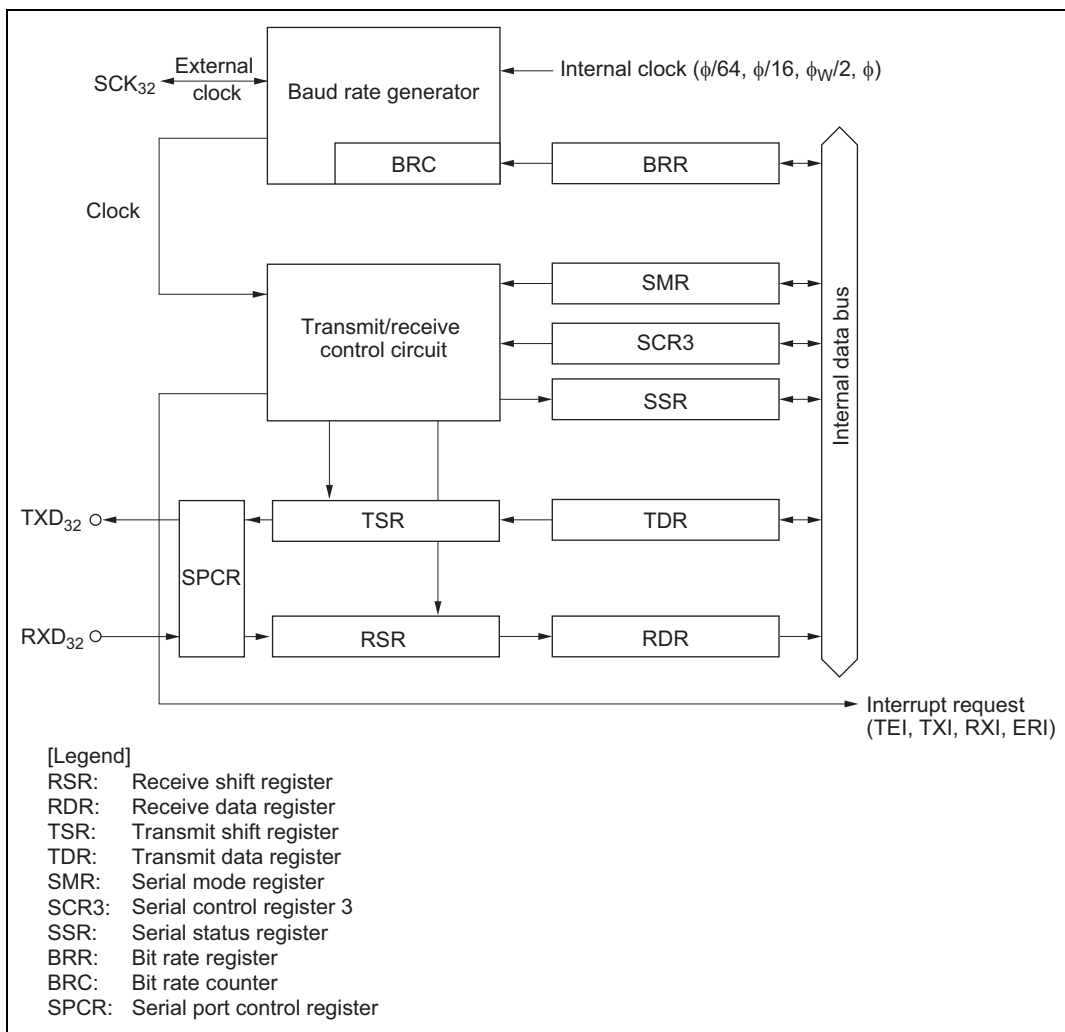


Figure 10.1 SCI3 Block Diagram

- Simultaneous transmit/receive

Figure 10.15 shows an example of a flowchart for a simultaneous transmit/receive operation. This procedure should be followed for simultaneous transmission/reception after initializing SCI3.

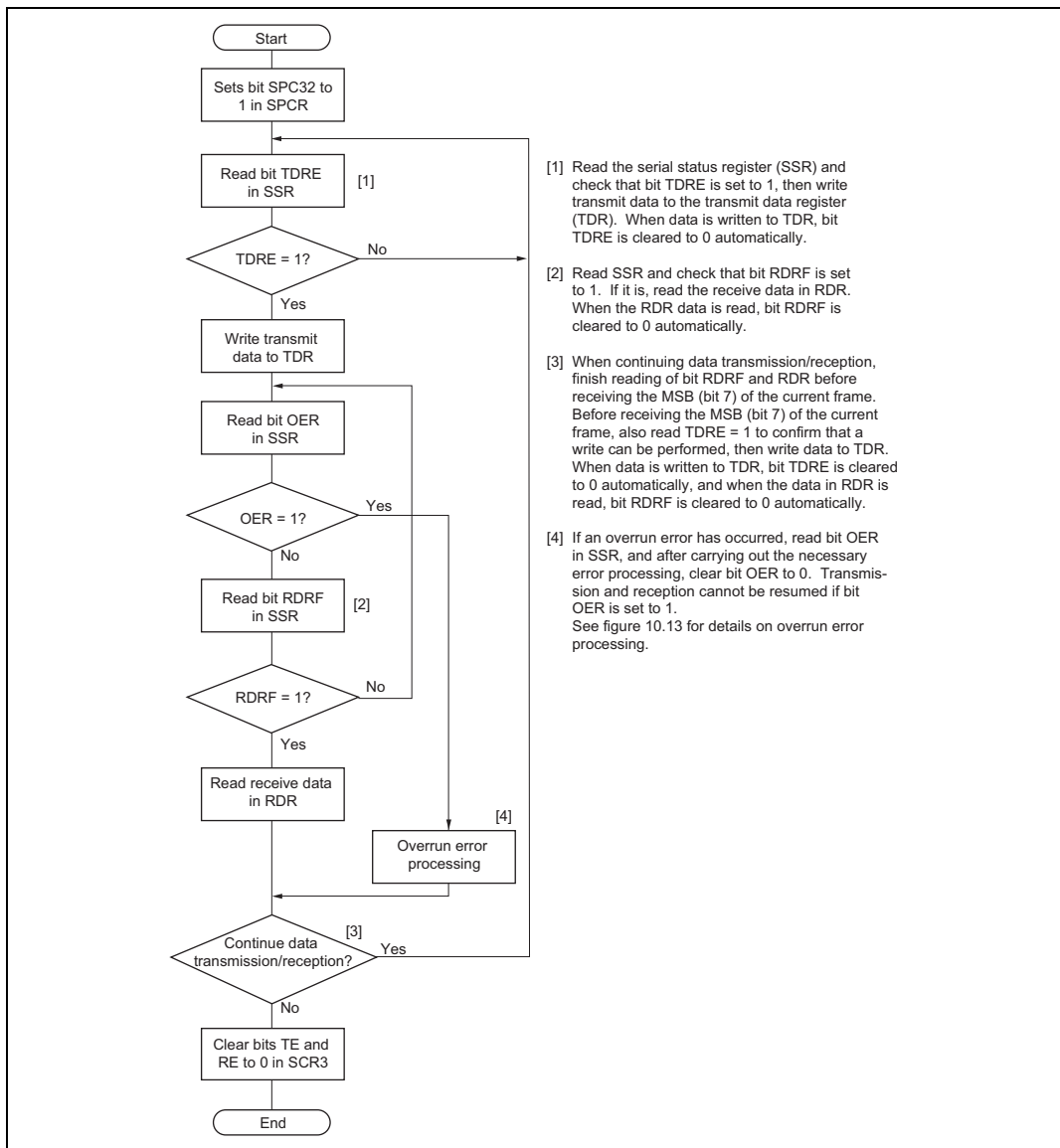


Figure 10.15 Example of Simultaneous Data Transmission/Reception Flowchart (Synchronous Mode)

15.2 When Not Using Internal Power Supply Step-Down Circuit

When the internal power supply step-down circuit is not used, connect the external power supply to the CV_{CC} pin and V_{CC} pin, as shown in figure 15.2. The external power supply is then input directly to the internal power supply. The permissible range for the power supply voltage is 2.7 V to 3.6 V. Operation cannot be guaranteed if a voltage outside this range (less than 3.0 V or more than 3.6 V) is input.

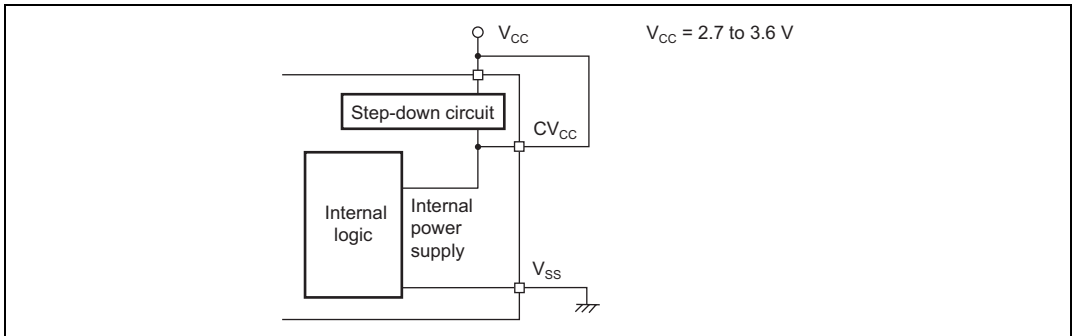
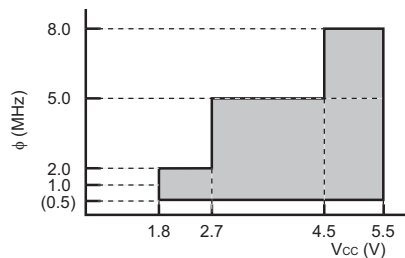


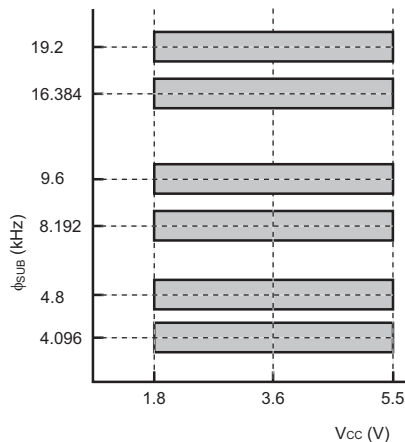
Figure 15.2 Power Supply Connection when Internal Step-Down Circuit is Not Used

Power Supply Voltage and Operating Frequency Range

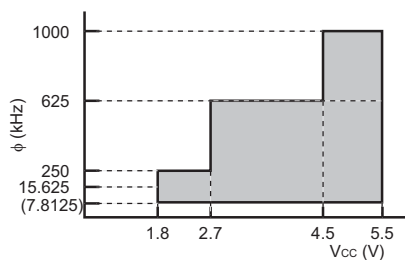


- Active (high-speed) mode
- Sleep (high-speed) mode (except CPU)

Note: 1. The figure in parentheses is the minimum operating frequency when an external clock is input. When using an oscillator, the minimum operating frequency (ϕ) is 1 MHz.



- Subactive mode
- Subsleep mode (except CPU)
- Watch mode (except CPU)



- Active (medium-speed) mode
- Sleep (medium-speed) mode (except A/D converter)

Note: 2. The figure in parentheses is the minimum operating frequency when an external clock is input. When using an oscillator, the minimum operating frequency (ϕ) is 15.625 kHz.

Item	Symbol	Applicable Pins	Values			Unit	Test Condition	Notes
			Min	Typ	Max			
Output low voltage	V_{OL}	P1 ₃ , P1 ₄ , P1 ₆ , P1 ₇ , P4 ₀ to P4 ₂	—	—	0.6	V	$V_{CC} = 4.0 \text{ V to } 5.5 \text{ V}$ $I_{OL} = 1.6 \text{ mA}$	
			—	—	0.5		$I_{OL} = 0.4 \text{ mA}$	
			—	—	0.5		$I_{OL} = 0.4 \text{ mA}$	
		P5 ₀ to P5 ₇ , P6 ₀ to P6 ₇ , P7 ₀ to P7 ₇ , P8 ₀ to P8 ₇ , PA ₀ to PA ₃	—	—	0.5			
		P3 ₀ to P3 ₇	—	—	1.5		$V_{CC} = 4.0 \text{ V to } 5.5 \text{ V}$ $I_{OL} = 10 \text{ mA}$	
			—	—	0.6		$V_{CC} = 4.0 \text{ V to } 5.5 \text{ V}$ $I_{OL} = 1.6 \text{ mA}$	
			—	—	0.5		$I_{OL} = 0.4 \text{ mA}$	
		P9 ₀ to P9 ₂	—	—	0.5		$V_{CC} = 2.2 \text{ to } 5.5 \text{ V}$ $I_{OL} = 25 \text{ mA}$	*5
							$I_{OL} = 15 \text{ mA}$	
			—	—	0.5		$I_{OL} = 10 \text{ mA}$	*6
		P9 ₃ to P9 ₅	—	—	0.5		$I_{OL} = 10 \text{ mA}$	
Input/output leakage current	$ I_{IL} $	RES, P4 ₃	—	—	20.0	μA	$V_{IN} = 0.5 \text{ V to } V_{CC} - 0.5 \text{ V}$	*2
			—	—	1.0			*1
		OSC ₁ , X ₁ , P1 ₃ , P1 ₄ , P1 ₆ , P1 ₇ , P3 ₀ to P3 ₇ , P4 ₀ to P4 ₂ , P5 ₀ to P5 ₇ , P6 ₀ to P6 ₇ , P7 ₀ to P7 ₇ , P8 ₀ to P8 ₇ , IRQAEC, P9 ₀ to P9 ₅ , PA ₀ to PA ₃	—	—	1.0	μA	$V_{IN} = 0.5 \text{ V to } V_{CC} - 0.5 \text{ V}$	
		PB ₀ to PB ₇	—	—	1.0		$V_{IN} = 0.5 \text{ V to } AV_{CC} - 0.5 \text{ V}$	

16.4.3 AC Characteristics

Table 16.9 lists the control signal timing, and tables 16.10 lists the serial interface timing of the H8/38024F.

Table 16.9 Control Signal Timing

$V_{CC} = 2.7\text{ V to }3.6\text{ V}$, $AV_{CC} = 2.7\text{ V to }3.6\text{ V}$, $V_{SS} = AV_{SS} = 0.0\text{ V}$

Item	Symbol	Applicable Pins	Values			Unit	Test Condition	Reference Figure
			Min	Typ	Max			
System clock oscillation frequency	f_{OSC}	OSC ₁ , OSC ₂	2.0	—	10.0	MHz		
OSC clock (ϕ_{OSC}) cycle time	t_{OSC}	OSC ₁ , OSC ₂	100	—	500 (1000)	ns		Figure 16.2 *2
System clock (ϕ) cycle time	t_{cyc}		2	—	128	t_{OSC}		
			—	—	128	μs		
Subclock oscillation frequency	f_W	X ₁ , X ₂	—	32.768 or 38.4	—	kHz		
Watch clock (ϕ_W) cycle time	t_W	X ₁ , X ₂	—	30.5 or 26.0	—	μs		Figure 16.2
Subclock (ϕ_{SUB}) cycle time	t_{subcyc}		2	—	8	t_W		*1
Instruction cycle time			2	—	—	t_{cyc} t_{subcyc}		
Oscillation stabilization time	t_{rc}	OSC ₁ , OSC ₂	—	0.8	2.0	ms	Figure 16.10 (crystal oscillator)	Figure 16.10 *3
			—	2.0	6.0	ms	Figure 16.9 (crystal oscillator)	Figure 16.9 *4
			—	20	45	μs	Figure 16.10 (ceramic oscillator)	Figure 16.10 *3
			—	20	45	μs	Figure 16.9 (ceramic oscillator)	Figure 16.9 *4
			—	—	50	ms	Except the above	
		X ₁ , X ₂	—	—	2.0	s		

Item	Symbol	Applicable Pins	Values			Unit	Test Condition	Notes
			Min	Typ	Max			
Active mode current dissipation	I _{OPe1}	V _{CC}	—	0.2	—	mA	Active (high-speed) mode V _{CC} = 1.8 V, f _{OSC} = 1 MHz	*1 *2 Max. guideline = 1.1 × typ.
			—	0.6	—	mA	Active (high-speed) mode V _{CC} = 3 V, f _{OSC} = 2 MHz	*1 *2 Max. guideline = 1.1 × typ.
			—	1.2	—	mA	Active (high-speed) mode V _{CC} = 3 V, f _{OSC} = 4 MHz	*1 *2 Max. guideline = 1.1 × typ.
			—	3.1	6.0	mA	Active (high-speed) mode V _{CC} = 3 V, f _{OSC} = 10 MHz	*1 *2
	I _{OPe2}	V _{CC}	—	0.03	—	mA	Active (medium-speed) mode V _{CC} = 1.8 V, f _{OSC} = 1 MHz φ _{osc} /128	*1 *2 Max. guideline = 1.1 × typ.
			—	0.1	—	mA	Active (medium-speed) mode V _{CC} = 3 V, f _{OSC} = 2 MHz φ _{osc} /128	*1 *2 Max. guideline = 1.1 × typ.

Table 16.18 Serial Interface (SCI3) Timing
 $V_{CC} = 1.8 \text{ V to } 3.6 \text{ V}$, $AV_{CC} = 1.8 \text{ V to } 3.6 \text{ V}$, $V_{SS} = AV_{SS} = 0.0 \text{ V}$

Item	Symbol	Values			Unit	Test Conditions	Reference Figure
		Min	Typ	Max			
Input clock cycle	Asynchronous	t_{scyc}	4	—	—	t_{cyc} or	Figure 16.5
	Synchronous	6	—	—	—	t_{subcyc}	
Input clock pulse width	t_{SCKW}	0.4	—	0.6	t_{scyc}		Figure 16.5
Transmit data delay time (synchronous)	t_{TXD}	—	—	1	t_{cyc} or t_{subcyc}		Figure 16.6
Receive data setup time (synchronous)	t_{RXS}	400.0	—	—	ns		Figure 16.6
Receive data hold time (synchronous)	t_{RXH}	400.0	—	—	ns		Figure 16.6

Instruction	Mnemonic	Instruction Fetch I	Branch Addr. Read J	Stack Operation K	Byte Data Access L	Word Data Access M	Internal Operation N
MOV	MOV.W Rs, @Rd	1				1	
	MOV.W Rs, @(d:16, Rd)	2				1	
	MOV.W Rs, @-Rd	1				1	2
	MOV.W Rs, @aa:16	2				1	
MULXU	MULXU.B Rs, Rd	1					12
NEG	NEG.B Rd	1					
NOP	NOP	1					
NOT	NOT.B Rd	1					
OR	OR.B #xx:8, Rd	1					
	OR.B Rs, Rd	1					
ORC	ORC #xx:8, CCR	1					
ROTL	ROTL.B Rd	1					
ROTR	ROTR.B Rd	1					
ROTXL	ROTXL.B Rd	1					
ROTXR	ROTXR.B Rd	1					
RTE	RTE	2		2			2
RTS	RTS	2		1			2
SHAL	SHAL.B Rd	1					
SHAR	SHAR.B Rd	1					
SHLL	SHLL.B Rd	1					
SHLR	SHLR.B Rd	1					
SLEEP	SLEEP	1					
STC	STC CCR, Rd	1					
SUB	SUB.B Rs, Rd	1					
	SUB.W Rs, Rd	1					
SUBS	SUBS.W #1, Rd	1					
	SUBS.W #2, Rd	1					
POP	POP Rd	1		1			2
PUSH	PUSH Rs	1		1			2
SUBX	SUBX.B #xx:8, Rd	1					
	SUBX.B Rs, Rd	1					
XOR	XOR.B #xx:8, Rd	1					
	XOR.B Rs, Rd	1					
XORC	XORC #xx:8, CCR	1					

Appendix D Port States in the Different Processing States

Table D.1 Port States Overview

Port	Reset	Sleep	Subsleep	Standby	Watch	Subactive	Active
P1 ₇ , P1 ₆ ^{*3} , P1 ₄ , P1 ₃	High impedance	Retained	Retained	High impedance ^{*1}	Retained	Functions	Functions
P3 ₇ to P3 ₀	High impedance	Retained	Retained	High impedance ^{*1}	Retained	Functions	Functions
P4 ₃ to P4 ₀	High impedance	Retained	Retained	High impedance	Retained	Functions	Functions
P5 ₇ to P5 ₀	High impedance	Retained	Retained	High impedance ^{*1} ^{*2}	Retained	Functions	Functions
P6 ₇ to P6 ₀	High impedance	Retained	Retained	High impedance ^{*1}	Retained	Functions	Functions
P7 ₇ to P7 ₀	High impedance	Retained	Retained	High impedance	Retained	Functions	Functions
P8 ₇ to P8 ₀	High impedance	Retained	Retained	High impedance	Retained	Functions	Functions
P9 ₅ to P9 ₀	High impedance	Retained	Retained	High impedance ^{*1}	Retained	Functions	Functions
PA ₃ to PA ₀	High impedance	Retained	Retained	High impedance	Retained	Functions	Functions
PB ₇ to PB ₀	High impedance	High impedance	High impedance	High impedance	High impedance	High impedance	High impedance

Notes: 1. High level output when MOS pull-up is in on state.
 2. In the HD64F38024 the previous pin state is retained.
 3. Not implemented on H8/38124 Group.

Product Type				Part No.	Mark Code	Package (Package Code)
H8/38024 Group	H8/38023	Mask ROM versions	Regular specifications	HD64338023H	HD64338023(***)H	80-pin QFP (FP-80A)
				HD64338023F	HD64338023(***)F	80-pin QFP (FP-80B)
				HD64338023W	HD64338023(***)W	80-pin TQFP (TFP-80C)
				HCD64338023	—	Die
		Wide-range specifications		HD64338023D	HD64338023(***)H	80-pin QFP (FP-80A)
				HD64338023E	HD64338023(***)F	80-pin QFP (FP-80B)
				HD64338023WI	HD64338023(***)W	80-pin TQFP (TFP-80C)
	H8/38022	Mask ROM versions	Regular specifications	HD64338022H	HD64338022(***)H	80-pin QFP (FP-80A)
				HD64338022F	HD64338022(***)F	80-pin QFP (FP-80B)
				HD64338022W	HD64338022(***)W	80-pin TQFP (TFP-80C)
				HCD64338022	—	Die
		Wide-range specifications		HD64338022D	HD64338022(***)H	80-pin QFP (FP-80A)
				HD64338022E	HD64338022(***)F	80-pin QFP (FP-80B)
				HD64338022WI	HD64338022(***)W	80-pin TQFP (TFP-80C)
	H8/38021	Mask ROM versions	Regular specifications	HD64338021H	HD64338021(***)H	80-pin QFP (FP-80A)
				HD64338021F	HD64338021(***)F	80-pin QFP (FP-80B)
				HD64338021W	HD64338021(***)W	80-pin TQFP (TFP-80C)
				HCD64338021	—	Die
		Wide-range specifications		HD64338021D	HD64338021(***)H	80-pin QFP (FP-80A)
				HD64338021E	HD64338021(***)F	80-pin QFP (FP-80B)
	H8/38020	Mask ROM versions	Regular specifications	HD64338020H	HD64338020(***)H	80-pin QFP (FP-80A)
				HD64338020F	HD64338020(***)F	80-pin QFP (FP-80B)
				HD64338020W	HD64338020(***)W	80-pin TQFP (TFP-80C)
				HCD64338020	—	Die
		Wide-range specifications		HD64338020D	HD64338020(***)H	80-pin QFP (FP-80A)
				HD64338020E	HD64338020(***)F	80-pin QFP (FP-80B)
				HD64338020WI	HD64338020(***)W	80-pin TQFP (TFP-80C)